

# SSM6K781G

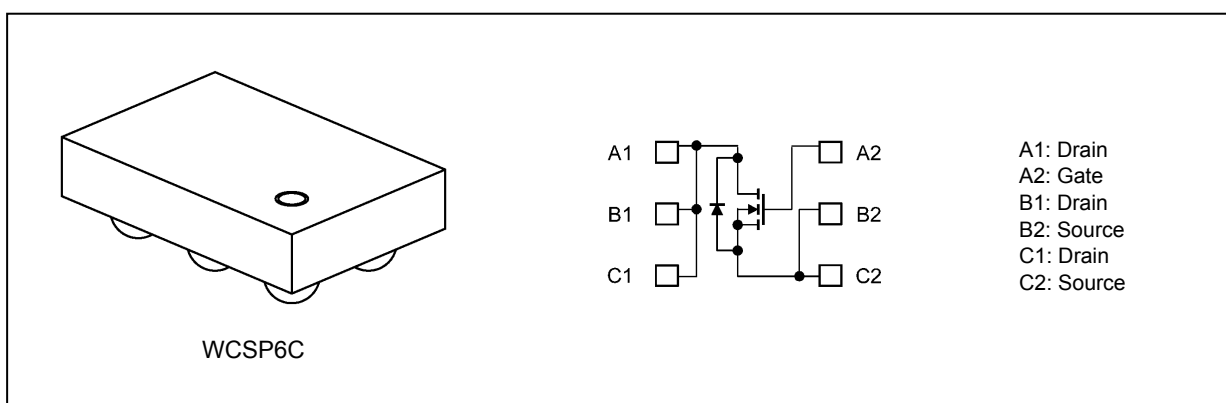
## 1. Applications

- Power Management Switches

## 2. Features

- (1) 1.5-V gate drive voltage.
- (2) Low drain-source on-resistance  
 $R_{DS(ON)} = 17.9 \text{ m}\Omega$  (typ.) (@ $V_{GS} = 2.5 \text{ V}$ ,  $I_D = 1.5 \text{ A}$ )  
 $R_{DS(ON)} = 14.4 \text{ m}\Omega$  (typ.) (@ $V_{GS} = 4.5 \text{ V}$ ,  $I_D = 1.5 \text{ A}$ )

## 3. Packaging and Pin Assignment



## 4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25 \text{ }^\circ\text{C}$ )

Characteristics	Symbol	Rating	Unit
Drain-source voltage	$V_{DSS}$	12	V
Gate-source voltage	$V_{GSS}$	$\pm 8$	
Drain current (DC) (Note 1)	$I_D$	7	A
Drain current (pulsed) (Note 1), (Note 2)	$I_{DP}$	14	
Power dissipation (Note 3)	$P_D$	1.6	W
Power dissipation ( $t \leq 10 \text{ s}$ ) (Note 3)	$P_D$	2.9	
Channel temperature	$T_{ch}$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-50 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed  $150 \text{ }^\circ\text{C}$ .

Note 2: Pulse width (PW)  $\leq 10 \text{ ms}$ , duty  $\leq 1\%$

Note 3: Device mounted on an FR4 board. (40.0 mm  $\times$  40.0 mm  $\times$  1.6 mm, Cu Pad: 1369 mm<sup>2</sup> 4 layer)

Start of commercial production

2013-09

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance,  $R_{th(ch-a)}$ , and the drain power dissipation,  $P_D$ , vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.

## 5. Electrical Characteristics

### 5.1. Static Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 8\text{ V}$ , $V_{DS} = 0\text{ V}$	—	—	$\pm 0.1$	$\mu\text{A}$
Drain cut-off current	$I_{DSS}$	$V_{DS} = 4.8\text{ V}$ , $V_{GS} = 0\text{ V}$	—	—	1	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = 0\text{ V}$	12	—	—	V
Drain-source breakdown voltage (Note 1)	$V_{(BR)DSX}$	$I_D = 250\text{ }\mu\text{A}$ , $V_{GS} = -5\text{ V}$	7	—	—	
Gate threshold voltage (Note 2)	$V_{th}$	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	0.4	—	1.0	V
Drain-source on-resistance (Note 3)	$R_{DS(ON)}$	$I_D = 1.5\text{ A}$ , $V_{GS} = 4.5\text{ V}$	—	14.4	18	$\text{m}\Omega$
		$I_D = 1.5\text{ A}$ , $V_{GS} = 2.5\text{ V}$	—	17.9	23.2	
		$I_D = 1.5\text{ A}$ , $V_{GS} = 1.8\text{ V}$	—	24.7	47.4	
		$I_D = 0.4\text{ A}$ , $V_{GS} = 1.5\text{ V}$	—	34	124	
Forward transfer admittance (Note 3)	$ Y_{fs} $	$V_{DS} = 6\text{ V}$ , $I_D = 1.5\text{ A}$	—	18	—	S

Note 1: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

Note 2: Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to below (1 mA for this device). Then, for normal switching operation,  $V_{GS(ON)}$  must be higher than  $V_{th}$ , and  $V_{GS(OFF)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$ .

Take this into consideration when using the device.

Note 3: Pulse measurement.

### 5.2. Dynamic Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	$C_{iss}$	$V_{DS} = 6\text{ V}$ , $V_{GS} = 0\text{ V}$ , $f = 1\text{ MHz}$	—	600	—	$\text{pF}$
Reverse transfer capacitance	$C_{rss}$		—	120	—	
Output capacitance	$C_{oss}$		—	250	—	
Switching time (turn-on time)	$t_{on}$	$V_{DD} = 6\text{ V}$ , $I_D = 1.5\text{ A}$ $V_{GS} = 0\text{ to }2.5\text{ V}$ , $R_G = 4\text{ }\Omega$ See Chapter 5.3.	—	17	—	$\text{ns}$
Switching time (turn-off time)	$t_{off}$		—	38	—	

### 5.3. Switching Time Test Circuit

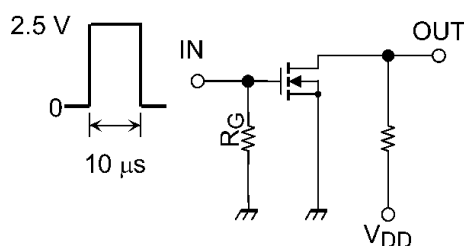


Fig. 5.3.1 Switching Time Test Circuit

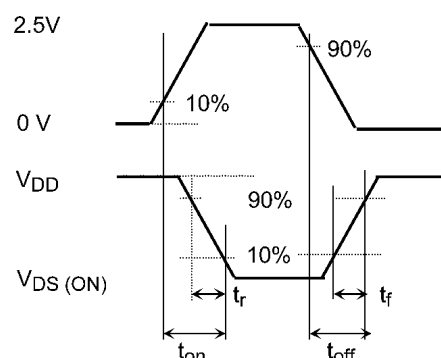


Fig. 5.3.2 Input Waveform/Output Waveform

### 5.4. Gate Charge Characteristics (Unless otherwise specified, $T_a = 25\text{ }^{\circ}\text{C}$ )

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	$Q_g$	$V_{DD} = 6\text{ V}$ , $V_{GS} = 4.5\text{ V}$ , $I_D = 1.5\text{ A}$	—	5.4	—	$\text{nC}$
Gate-source charge 1	$Q_{gs1}$		—	1.3	—	
Gate-drain charge	$Q_{gd}$		—	1.0	—	

5.5. Source-Drain Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Diode forward voltage (Note 1)	V <sub>DSF</sub>	I <sub>D</sub> = -1.5 A, V <sub>GS</sub> = 0 V	—	-0.65	-1.0	V

Note 1: Pulse measurement.

6. Marking

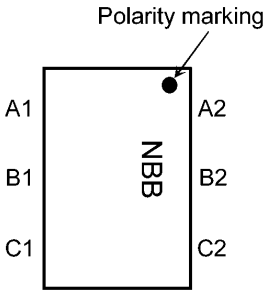


Fig. 6.1 Marking

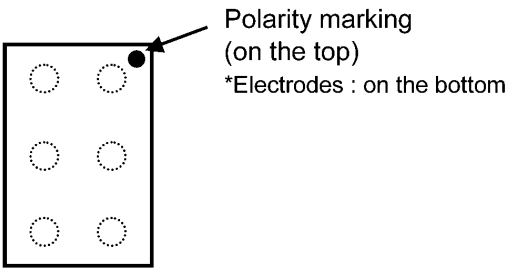
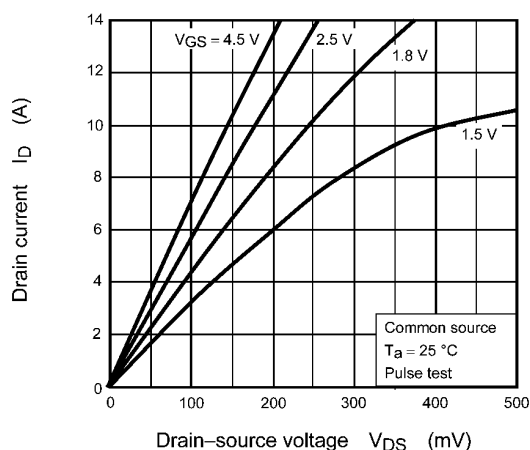
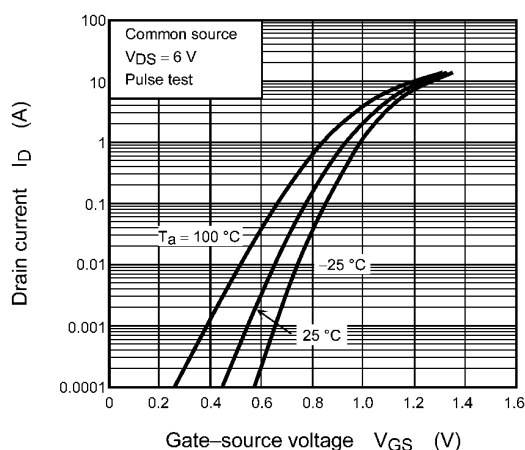


Fig. 6.2 Pin Condition(Top View)

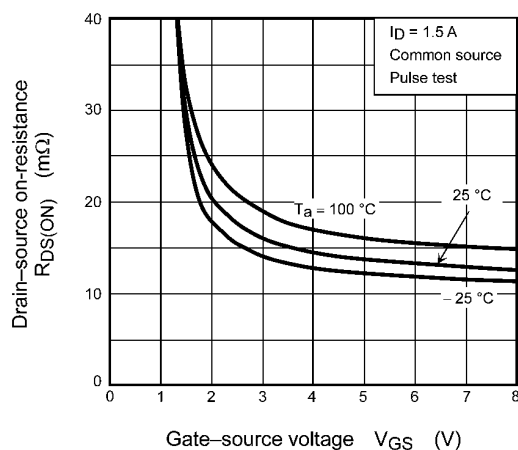
# 7. Characteristics Curves (Note)



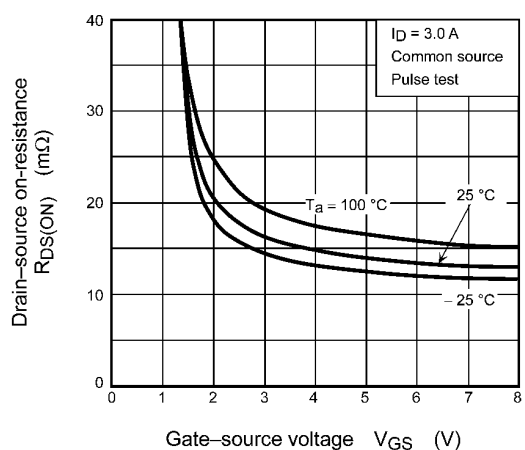
**Fig. 7.1  $I_D - V_{DS}$**



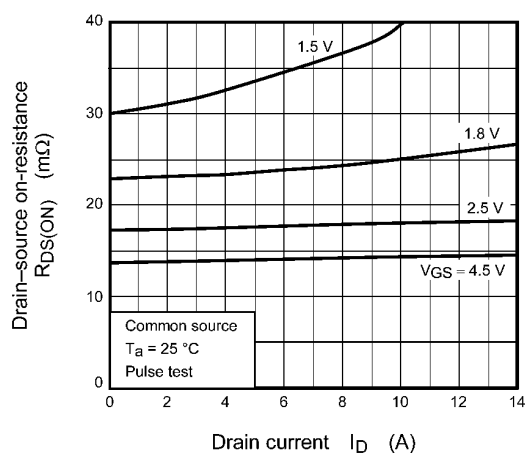
**Fig. 7.2  $I_D - V_{GS}$**



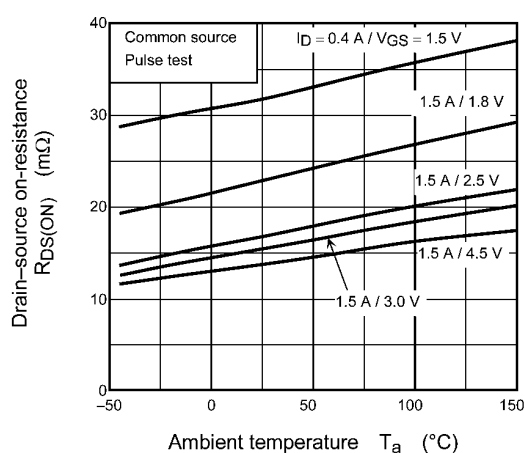
**Fig. 7.3  $R_{DS(ON)} - V_{GS}$**



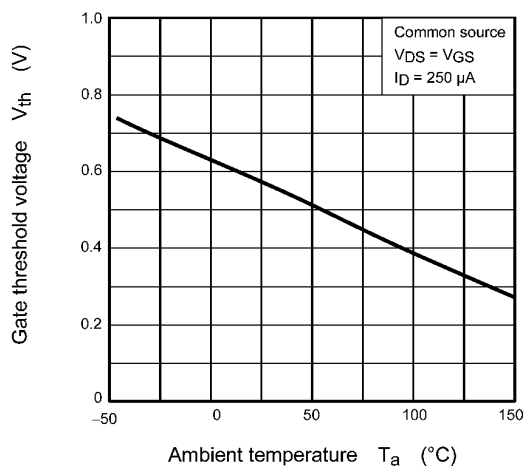
**Fig. 7.4  $R_{DS(ON)} - V_{GS}$**



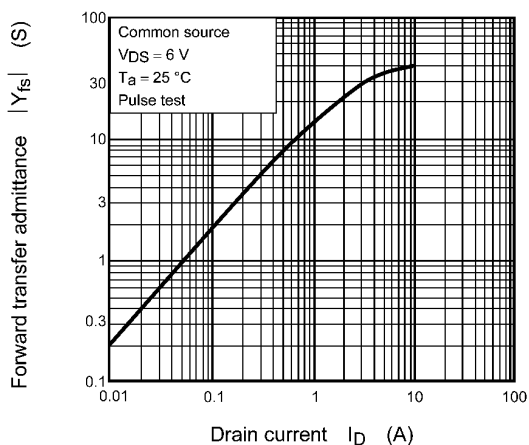
**Fig. 7.5  $R_{DS(ON)} - I_D$**



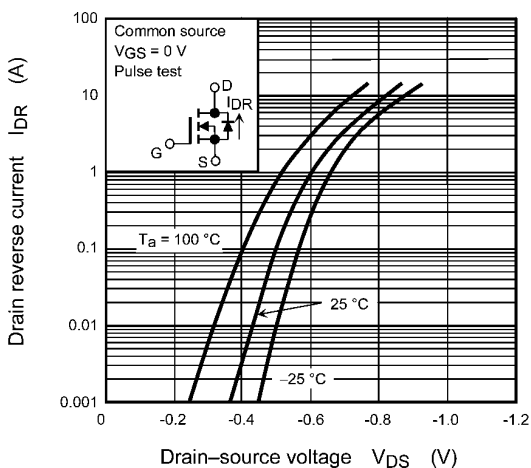
**Fig. 7.6  $R_{DS(ON)} - T_a$**



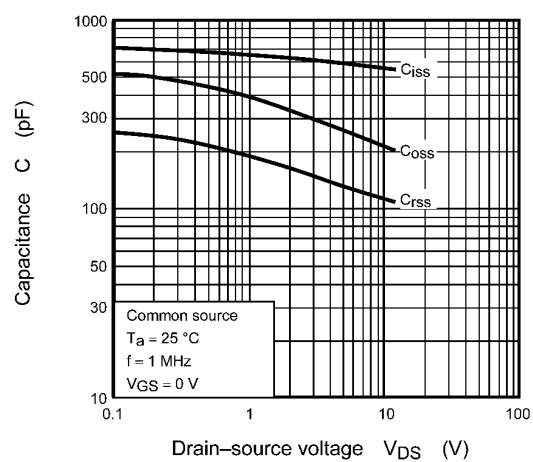
**Fig. 7.7  $V_{th} - T_a$**



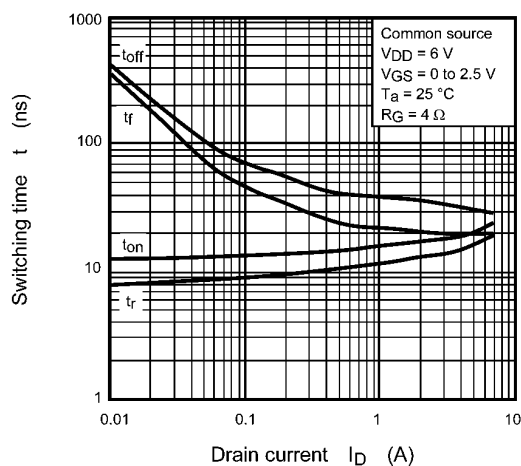
**Fig. 7.8  $|Y_{fs}| - I_D$**



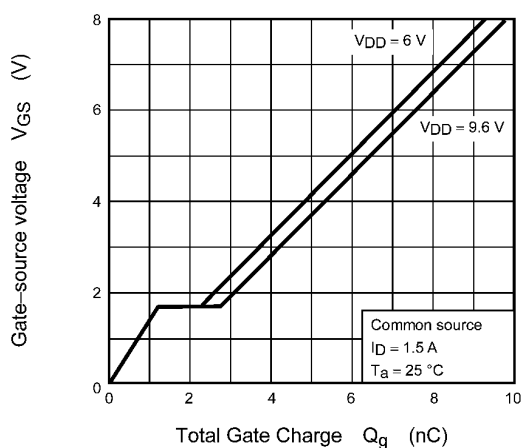
**Fig. 7.9  $I_{DR} - V_{DS}$**



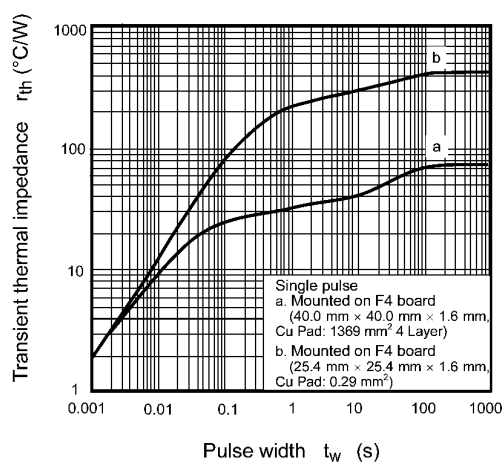
**Fig. 7.10  $C - V_{DS}$**



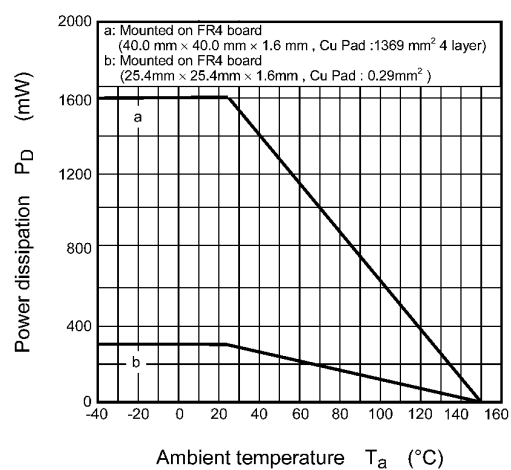
**Fig. 7.11  $t - I_D$**



**Fig. 7.12 Dynamic Input Characteristics**



**Fig. 7.13**  $r_{th} - t_w$

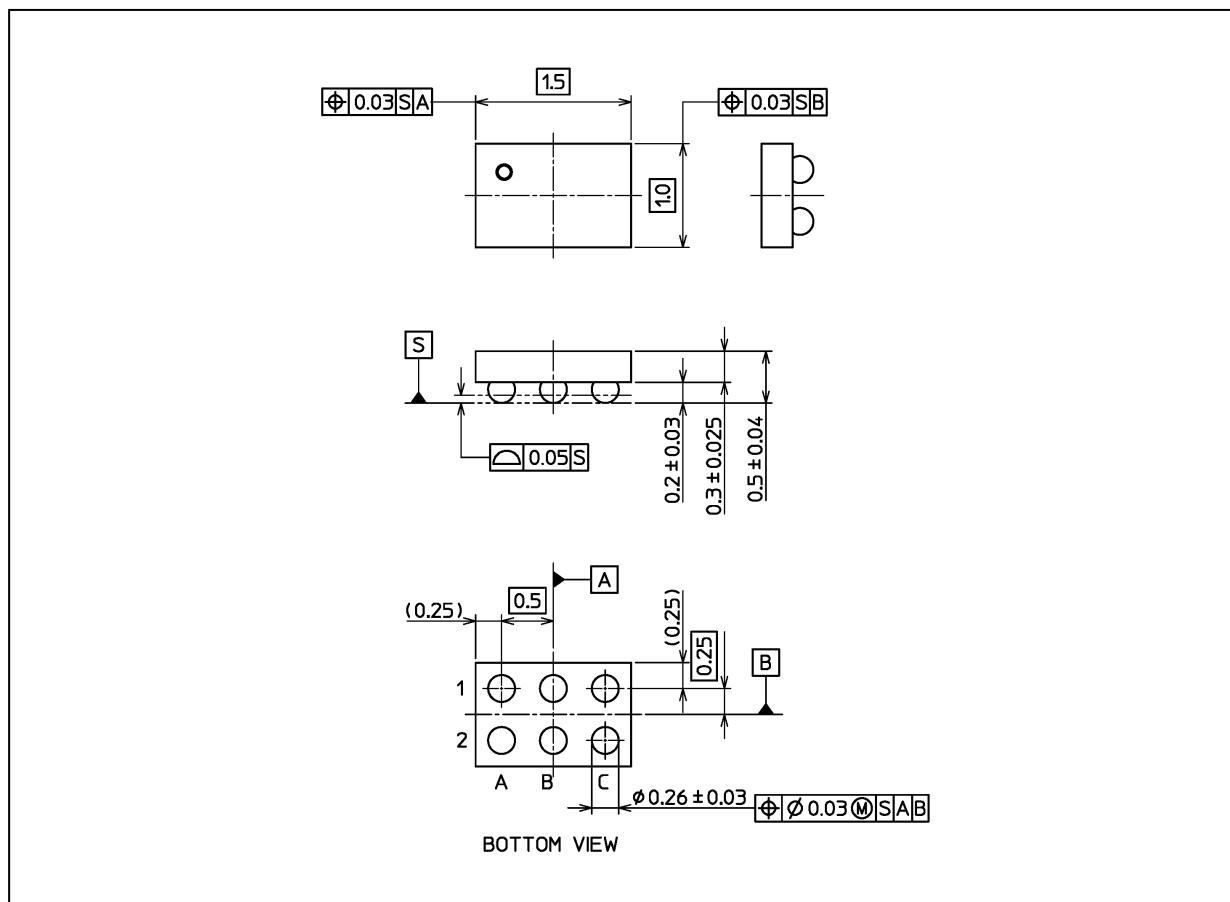


**Fig. 7.14**  $P_D - T_a$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

## Package Dimensions

Unit: mm



Weight: 1.4 mg (typ.)

Package Name(s)
Nickname: WCSP6C



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